

## Brioccean Quality Control Center

With a combined space of around **1,000 square meters**, over **60 professional inspection tools** and more than **50 professional inspection engineers**, Brioccean has created two top-notch quality control centers in **Shenzhen** and **Hong Kong**. The Quality Control Centers of Brioccean have the ability to professionally test the physical and electronic performance of various electronic components.

### Stringent Quality Inspection Process

In order to ensure that each electronic component meets the required **quality standards**, Brioccean inspects, verifies, and tests them starting with the packaging. The **quality of every component** sourced is something that Brioccean continues to pay close attention to.



Labelling and Packaging Verification

01  
TIER



Visual and Marking Inspection

02  
TIER



Functional and Reliability Testing

03  
TIER



Third Party Inspection

04  
TIER

Find out more at:  
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#### CERTIFICATIONS



# 10 Professional Testing Services

Our comprehensive **4-tier quality inspection process** consists of **10 professional testing services** to ensure no defects or abnormalities are left undetected.



## X-Ray Non-Destructive Flaw Inspection

Conduct real-time non-destructive analysis to inspect the hardware within the component to detect lead frame of the chip, wafer size, gold wire binding diagram, ESD's holes and damage.



## Static Parameter Test

Set the relevant parameters according to the datasheet to ensure the actual value of the passive components is within the acceptable error range.



## Impedance Analysis Test

To verify that there is no deviation between the impedance value and specification difference of impedance devices.



## ESD Anti-Static Test

To verify the surface impedance co-efficiency, grounding resistance, the instantaneous value and peak value of electrostatic potential of objects such as electrostatic protection materials, device packaging and insulating materials.



## Solderability Testing

Check if the tinning ability of the chip pin meets the J-STD-002B standard.



## High Temperature Aging

Provides standardised and professional baking and vacuum packaging to avoid moisture damage to the chip, control the temperature of the solder reflow to maintain the usability and reliability of the chip.



## XRF Elemental Measurement and Analysis

To conduct XRF analysis to ensure the component's materials are compliant with RoHS regulations.



## Decapsulation

Provides decapping service to remove the die completely to check the screen printing, logo information on the wafer, ensuring authenticity of component.



## SAM Failure Analysis

Ultrasonic scanning to identify interior materials of electronic component such as delamination, cracks, voids, silicon wafer tilt and foreign contaminants.



## MCU Programming Test

Conduct programming testing to ensure components have not been programmed and are in their original factory configuration.

## High-end Testing Equipment



\*Not limited to the above-mentioned equipment